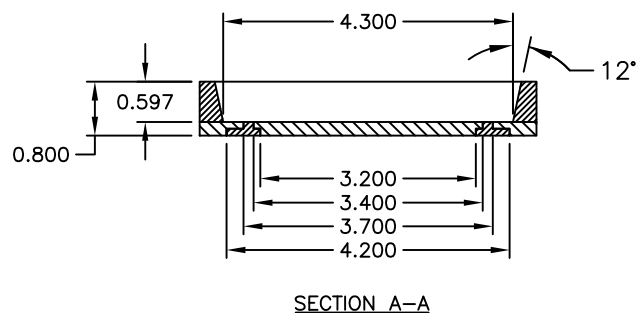
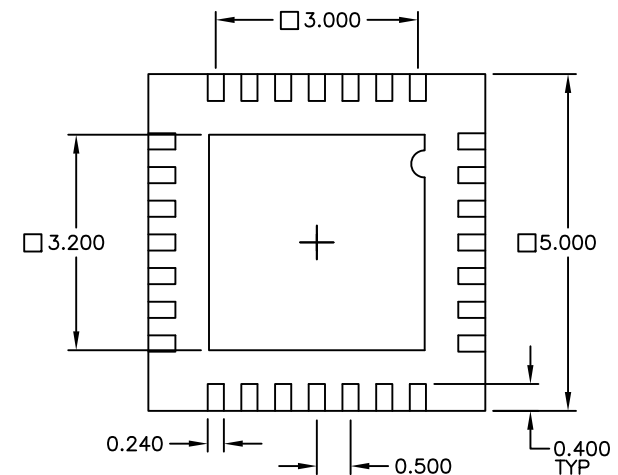
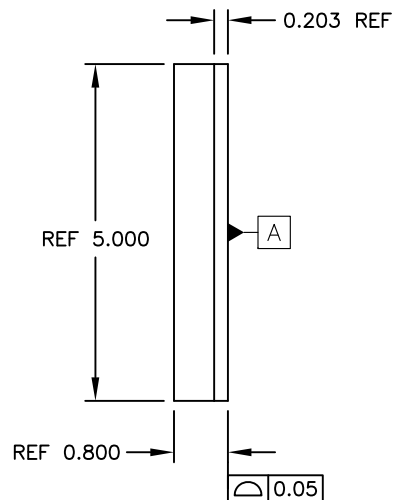
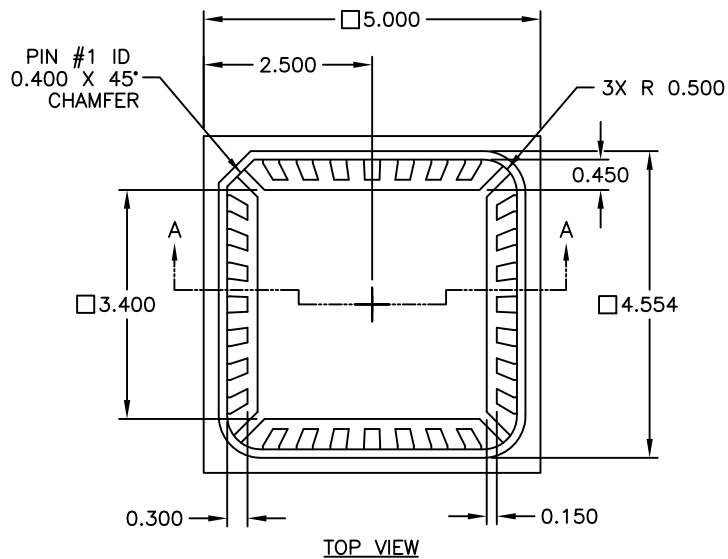


2

1

REVISIONS			
ECN NO.	DATE	DESCRIPTION	APPROVED



NOTES

1. MATERIALS:

LEAD FRAME: COPPER 194FH, THK = 0.203±0.008
 BODY: SEMICONDUCTOR MOLDING EPOXY, CONTACT SPECTRUM FOR DETAILS.

2. FINISH:

LEAD FRAME: ELECTROLESS NICKEL PER MIL-C-26074, CLASS 1, 100 TO 300 MICROINCHES (2.5um - 7.6um) THICK.
 GOLD PLATE PER MIL-G-45204, TYPE 3, GRADE A, CLASS 1 (40 TO 80 MICROINCHES (1um - 2um) THICK).
 BODY SURFACE FINISH: VDI 21-24 (1.12-1.6 Ra).

3. PACKAGE MISMATCH: BODY OFFSET TO LEAD FRAME = 0.076mm MAX

4. UNLESS OTHERWISE SPECIFIED, RADIUS ON ALL MOLDED EDGES AND CORNERS = 0.25mm MAX.

5. PACKAGE CONFORMS TO JEDEC MO-220.

Spectrum Semiconductor Materials, Inc.

www.spectrum-semi.com

155 Nicholson Lane

San Jose, CA 95134

PHONE: (408) 435-5555 FAX: (408) 435-8226

5mm X 5mm
 QFN 28 LEAD 0mPP

THIRD ANGLE PROJECTION

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETER TOLERANCES ARE:

X.XX ± 0.15 X.XXXX ± ----

X.XXX ± 0.050 ANGLES: ± 1°

DO NOT SCALE DRAWING

DRAWN BY	MWK	DATE	7/1/11
APP BY	SJO	DATE	7/1/11

MADE IN USA

SIZE	PART NO.	REV
A	QFN02804	A1
SCALE	CAD FILE	SHEET 1 OF 1
NONE		

2

1